

ABSTRACT

RESIN COMPOSITION, RESIN COMPOSITION FILM, CURED FILM,
HOLLOW STRUCTURE USING SAME, AND SEMICONDUCTOR DEVICE

In order to provide a resin composition excellent in pattern processability and film strength, a resin composition film, and a semiconductor device using these, there is provided a resin composition including (A) a polymer compound, (B) a cationic polymerizable compound, and (C) a cationic polymerization initiator, in which (A) the polymer compound has a carboxylic acid residue at a molecular chain terminal.

[No Suitable Figure]